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Quick Reference

Search by part #

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Products

Browse Heat sinks

- By Device -

- By Product Line -

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Useful Links

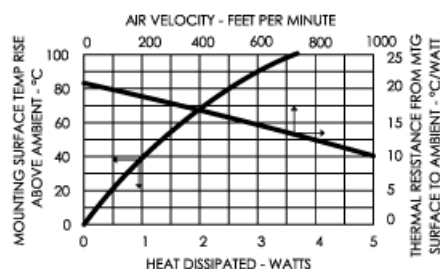
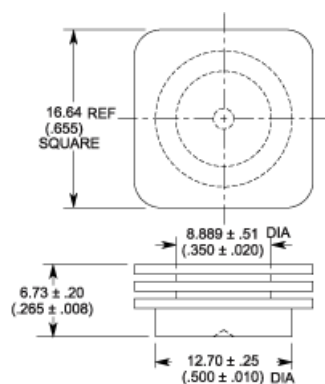
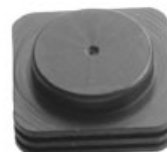
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[Products](#) / [BGA](#) / [Radial Fins](#)

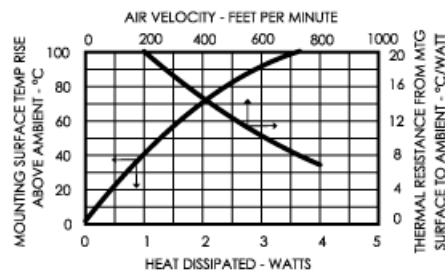
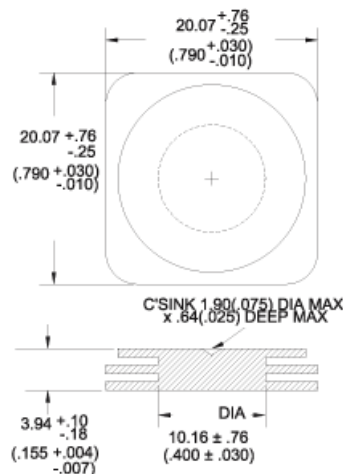
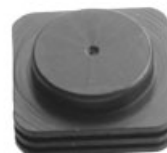
Radial Fin Heat Sinks for Microprocessors

- Bond-on heat sinks for leadless chip carriers and flat packs.
- Primarily designed for 68-position devices.
- The 2283 is ideally suited to limited board space applications with high air flow.

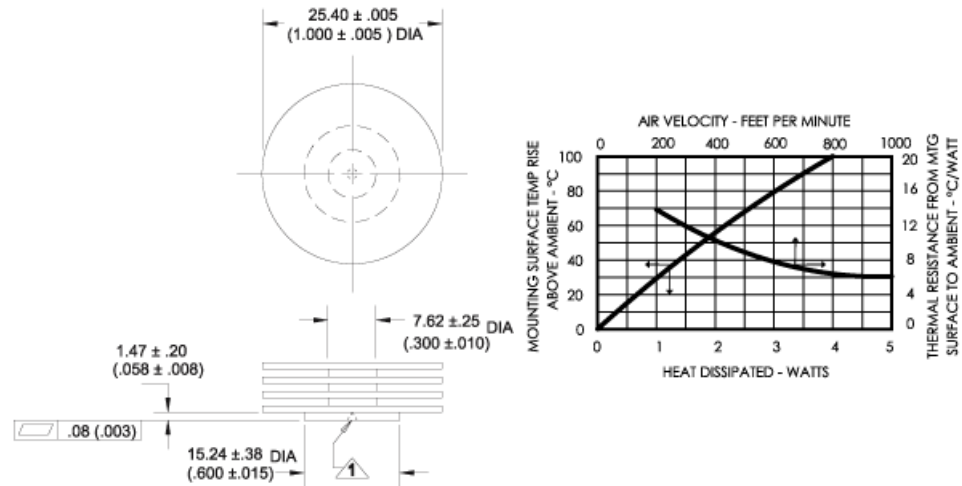
Part Number: 2283BG



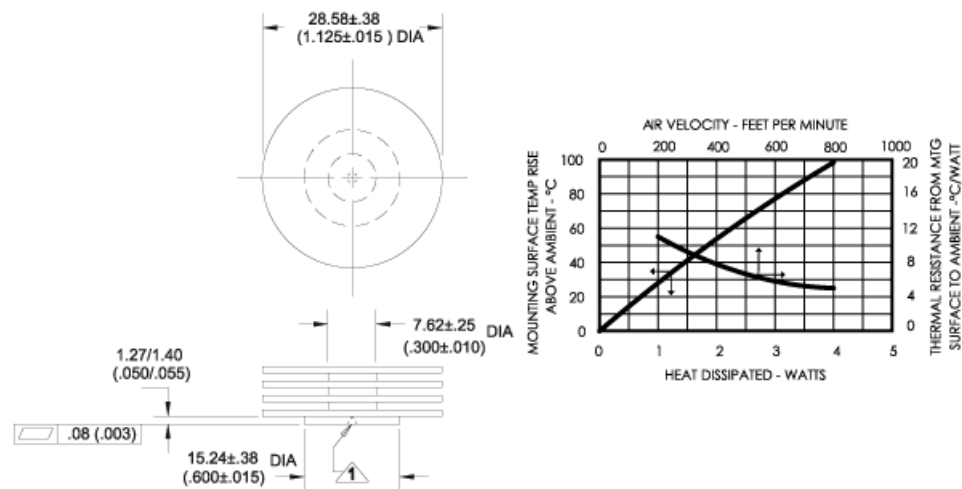
Part Number: 2286BG<



Part Number: 2288BG



Part Number: 2292BG

RoHS  Compliant

Part Number: 2296BG



